RELIABILITY REPORT

FOR

MAX336EAI+

PLASTIC ENCAPSULATED DEVICES

March 2, 2015

MAXIM INTEGRATED

160 RIO ROBLES
SAN JOSE, CA 95134

Approved by
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Quality Assurance
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Conclusion

The MAX336EAI+ successfully meets the quality and reliability standards required of all Maxim Integrated products. In addition, Maxim Integrated's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim Integrated's quality and reliability standards.

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I. Device Description

A. General

The MAX336/MAX337 are monolithic, CMOS analog multiplexers (muxes). The 16-channel MAX336 is designed to connect one of 16 inputs to a common output by control of a 4-bit binary address. The dual,8-channel MAX337 is designed to connect one of eight inputs to a common output by control of a 3-bit binary address. Both devices can be used as either a mux or a demux. On-resistance is 400 (max), and the devices conduct current equally well in both directions. These muxes feature extremely low off leakages (less than 20pA at +25°C) and on-channel leakages (less than 50pA at +25°C). The new design offers guaranteed low charge injection (3.5pC typical) and electrostatic discharge (ESD) protection greater than 2000V, per method 3015.7. These improved muxes are pin-compatible upgrades for the industry-standard DG506 and DG507. The MAX336/MAX337 operate from a single +4.5V to +30V supply or from dual ±4.5V to ±20V supplies. All control inputs (whether address or enable) are TTL compatible (0.8V to 2.4V) over the full specified temperature range and over the ±4.5V to ±18V supply range.

II. Manufacturing Information

A. Description/Function:	16-Channel Dual 8 Channel, Low Leakage, CMOS Analog Multiplexers
B. Process:	S5
C. Number of Device Transistors:	
D. Fabrication Location:	Oregon
E. Assembly Location:	Philippines, Malaysia
F. Date of Initial Production:	April 25, 1997

III. Packaging Information

A. Package Type:	28-pin SSOP
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Conductive
E. Bondwire:	Au (1.3 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-0301-0809
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Ja:	110°C/W
K. Single Layer Theta Jc:	25°C/W
L. Multi Layer Theta Ja:	67.1°C/W
M. Multi Layer Theta Jc:	25°C/W

IV. Die Information

A. Dimensions:	139X92 mils
B. Passivation:	Si_3N_4/SiO_2 (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Al/0.5%Cu with Ti/TiN Barrier
D. Backside Metallization:	None
E. Minimum Metal Width:	5.0 microns (as drawn)
F. Minimum Metal Spacing:	5.0 microns (as drawn)
G. Bondpad Dimensions:	
H. Isolation Dielectric:	SiO_2
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

A. Quality Assurance Contacts:	Don Lipps (Manager, Reliability Engineering) Bryan Preeshl (Vice President of QA)
B. Outgoing Inspection Level:	0.1% for all electrical parameters guaranteed by the Datasheet. 0.1% for all Visual Defects.
C. Observed Outgoing Defect Rate:	< 50 ppm
D. Sampling Plan:	Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135C biased (static) life test are shown in Table 1. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{1.83}{192 \times 4340 \times 275 \times 2} \quad \text{(Chi square value for MTTF upper limit)}$$

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$\lambda = 4.0 \times 10^{-9}$

λ = 4.0 F.I.T. (60% confidence level @ 25°C)

The following failure rate represents data collected from Maxim Integrated's reliability monitor program. Maxim Integrated performs quarterly life test monitors on its processes. This data is published in the Reliability Report found at http://www.maximintegrated.com/qa/reliability/monitor. Cumulative monitor data for the S5 Process results in a FIT Rate of 0.09 @ 25C and 1.53 @ 55C (0.8 eV, 60% UCL)

B. E.S.D. and Latch-Up Testing (lot XZOABQ001A, D/C 0715)

The AG86 die type has been found to have all pins able to withstand a HBM transient pulse of +/-2000V per Mil-Std 883 Method 3015.7. Latch-Up testing has shown that this device withstands a current of +/-250mA.

Table 1

Reliability Evaluation Test Results

MAX336EAI+

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES	COMMENTS
Static Life Test (Note 1)					
	Ta = 135°C	DC Parameters	38	0	NZOBC1001H, D/C 0001
	Biased	& functionality	80	0	XZOAAQ001A, D/C 9705
	Time = 192 hrs.		77	0	XZOABQ001A, D/C 9715
			80	0	XZOBBQ001A, D/C 9715

Note 1: Life Test Data may represent plastic DIP qualification lots.